

**TOSHIBA****TC74HC367,368AP/AF/AFN**

TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

**TC74HC367AP, TC74HC367AF, TC74HC367AFN  
TC74HC368AP, TC74HC368AF, TC74HC368AFN**
**HEX BUS BUFFER**
**TC74HC367AP/AF/AFN** NON-INVERTED (3-STATE)  
**TC74HC368AP/AF/AFN** INVERTED (3-STATE)

(Note) The JEDEC SOP (FN) is not available in Japan.

The TC74HC367A and TC74HC368A are high speed CMOS 3-STATE BUS BUFFERS fabricated with silicon gate C2MOS technology.

They achieve the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

They contain six buffers; four buffers are controlled by an enable input ( $\bar{G}_1$ ), and the other two buffers are controlled by another enable input ( $\bar{G}_2$ ). The outputs of each buffer group are enabled when  $\bar{G}_1$  and/or  $\bar{G}_2$  inputs are held low; if held high, these outputs are in a high impedance state.

The TC74HC367A is a non-inverting output type, while the TC74HC368A is an inverting output type.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

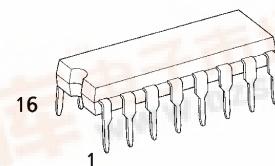
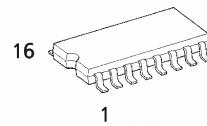
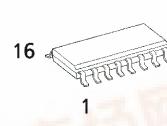
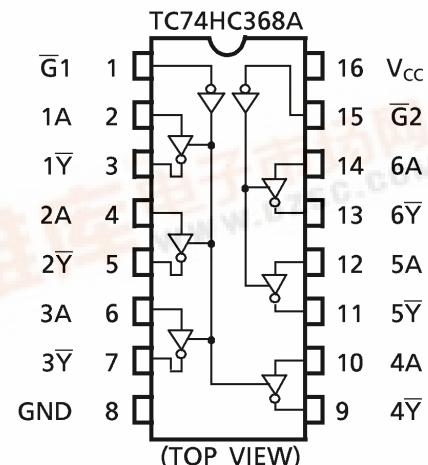
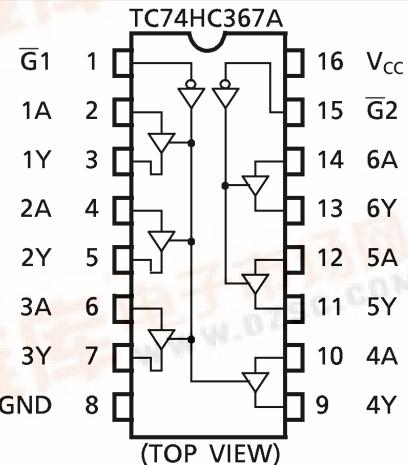
**FEATURES :**

- High Speed..... $t_{pd} = 11\text{ns}(\text{typ.})$  at  $V_{CC} = 5\text{V}$
- Low Power Dissipation..... $I_{CC} = 4\mu\text{A}(\text{Max.})$  at  $T_a = 25^\circ\text{C}$
- High Noise Immunity..... $V_{NIH} = V_{NIL} = 28\%$   $V_{CC}$  (Min.)
- Output Drive Capability..... 15 LSTTL Loads
- Symmetrical Output Impedance.....  $|I_{OH}| = I_{OL} = 6\text{mA}$
- Balanced Propagation Delays.....  $t_{pLH} \approx t_{pHL}$
- Wide Operating Voltage Range.....  $V_{CC}$  (opr.) =  $2\text{V} \sim 6\text{V}$
- Pin and Function Compatible with 74LS367/368

**TRUTH TABLE**

INPUTS		OUTPUTS	
$\bar{G}$	$A_n$	$Y(367A)$	$\bar{Y}(368A)$
L	L	L	H
L	H	H	L
H	X	Z	Z

X : Don't Care, Z : High Impedance

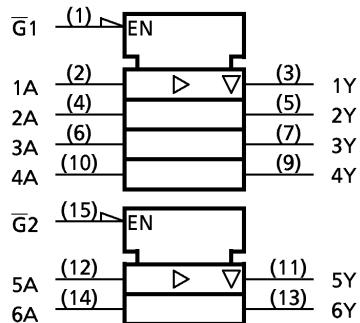
P (DIP16-P-300-2.54A)  
Weight : 1.00g (Typ.)F (SOP16-P-300-1.27)  
Weight : 0.18g (Typ.)FN (SOL16-P-150-1.27)  
Weight : 0.13g (Typ.)**PIN ASSIGNMENT**

961001EBA2

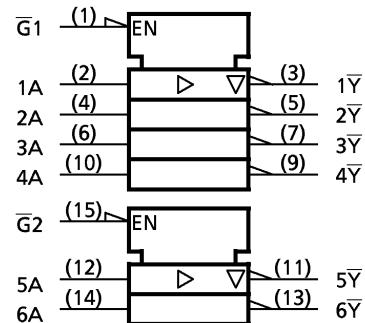
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## IEC LOGIC SYMBOL

TC74HC367A

HEX BUS BUFFER  
(3 - STATE)

TC74HC368A

HEX BUS BUFFER  
(3 - STATE / INV.)

961001EBA2'

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## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	$V_{CC}$	-0.5~7	V
DC Input Voltage	$V_{IN}$	-0.5~ $V_{CC} + 0.5$	V
DC Output Voltage	$V_{OUT}$	-0.5~ $V_{CC} + 0.5$	V
Input Diode Current	$I_{IK}$	$\pm 20$	mA
Output Diode Current	$I_{OK}$	$\pm 20$	mA
DC Output Current	$I_{OUT}$	$\pm 35$	mA
DC $V_{CC}$ /Ground Current	$I_{CC}$	$\pm 75$	mA
Power Dissipation	$P_D$	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	$T_{STG}$	-65~150	°C

\*500mW in the range of  $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$ . From  $T_a = 65^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  a derating factor of  $-10\text{mW}/^{\circ}\text{C}$  shall be applied until 300mW.

## RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	$V_{CC}$	2~6	V
Input Voltage	$V_{IN}$	0~ $V_{CC}$	V
Output Voltage	$V_{OUT}$	0~ $V_{CC}$	V
Operating Temperature	$T_{opr}$	-40~85	°C
Input Rise and Fall Time	$t_r, t_f$	0~1000 ( $V_{CC} = 2.0\text{V}$ ) 0~500 ( $V_{CC} = 4.5\text{V}$ ) 0~400 ( $V_{CC} = 6.0\text{V}$ )	ns

## DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	$V_{CC}$ (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	$V_{IH}$		2.0 4.5 6.0	1.50 3.15 4.20	— — —	— — —	1.50 3.15 4.20	— — —	V
Low - Level Input Voltage	$V_{IL}$		2.0 4.5 6.0	— — —	— — —	0.50 1.35 1.80	— — —	0.50 1.35 1.80	V
High - Level Output Voltage	$V_{OH}$	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OH} = -20\mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	2.0 4.5 6.0	— — —	1.9 4.4 5.9	— — —
			$I_{OH} = -6\text{ mA}$ $I_{OH} = -7.8\text{ mA}$	4.5 6.0	4.18 5.68	4.31 5.80	— —	4.13 5.63	— —
			$I_{OL} = 20\mu\text{A}$	2.0 4.5 6.0	— — —	0.0 0.0 0.0	0.1 0.1 0.1	— — —	0.1 0.1 0.1
Low - Level Output Voltage	$V_{OL}$	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OL} = 6\text{ mA}$ $I_{OL} = 7.8\text{ mA}$	4.5 6.0	— —	0.17 0.18	0.26 0.26	— —	0.33 0.33
			$I_{OL} = 20\mu\text{A}$	2.0 4.5 6.0	— — —	0.0 0.0 0.0	0.1 0.1 0.1	— — —	0.1 0.1 0.1
3 - State Output Off - State Current	$I_{OZ}$	$V_{IN} = V_{IH}$ or $V_{IL}$ $V_{OUT} = V_{CC}$ or GND	6.0	—	—	$\pm 0.5$	—	$\pm 5.0$	$\mu\text{A}$
Input Leakage Current	$I_{IN}$	$V_{IN} = V_{CC}$ or GND	6.0	—	—	$\pm 0.1$	—	$\pm 1.0$	
Quiescent Supply Current	$I_{CC}$	$V_{IN} = V_{CC}$ or GND	6.0	—	—	4.0	—	40.0	

AC ELECTRICAL CHARACTERISTICS (Input  $t_r = t_f = 6\text{ns}$ )

PARAMETER	SYMBOL	TEST CONDITION	$T_a = 25^\circ\text{C}$			$T_a = -40\text{--}85^\circ\text{C}$		UNIT	
			CL	$V_{CC}(\text{V})$	MIN.	TYP.	MAX.		
Output Transition Time	$t_{TLH}$		50	2.0	—	25	60	—	75
	$t_{THL}$			4.5	—	7	12	—	15
				6.0	—	6	10	—	13
Propagation Delay Time	$t_{pLH}$		50	2.0	—	36	95	—	120
				4.5	—	12	19	—	24
				6.0	—	10	16	—	20
	$t_{pHL}$		150	2.0	—	40	130	—	165
				4.5	—	16	26	—	33
				6.0	—	14	22	—	28
Output Enable Time	$t_{pZL}$	$R_L = 1\text{k}\Omega$	50	2.0	—	36	120	—	150
	$t_{pZH}$			4.5	—	12	24	—	30
				6.0	—	10	20	—	26
	$t_{pLZ}$		150	2.0	—	40	160	—	200
	$t_{pHZ}$			4.5	—	16	32	—	40
				6.0	—	14	27	—	34
Output Disable Time	$t_{pDZ}$	$R_L = 1\text{k}\Omega$	50	2.0	—	35	120	—	150
	$t_{pHZ}$			4.5	—	15	24	—	30
				6.0	—	13	20	—	26
Input Capacitance	$C_{IN}$				—	5	10	—	10
Output Capacitance	$C_{OUT}$				—	10	—	—	—
Power Dissipation Capacitance	$C_{PD}(1)$	TC74HC367A			—	36	—	—	—
		TC74HC368A			—	30	—	—	—

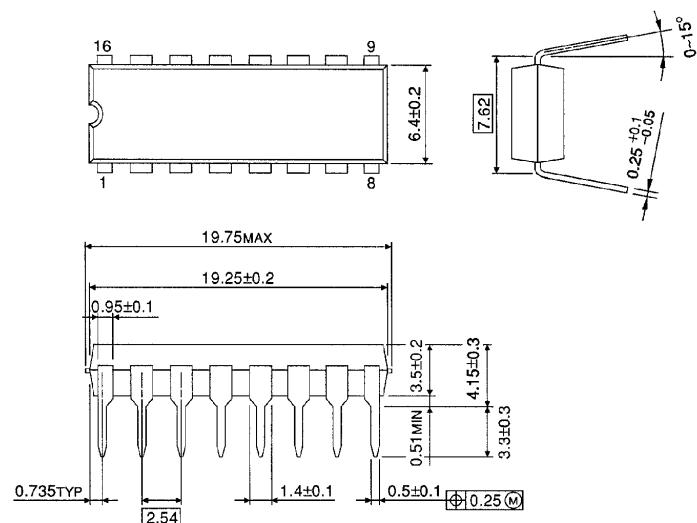
Note (1)  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{CC(\text{opr})} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/6 \text{ (per bit)}$$

**DIP 16PIN OUTLINE DRAWING (DIP16-P-300-2.54A)**

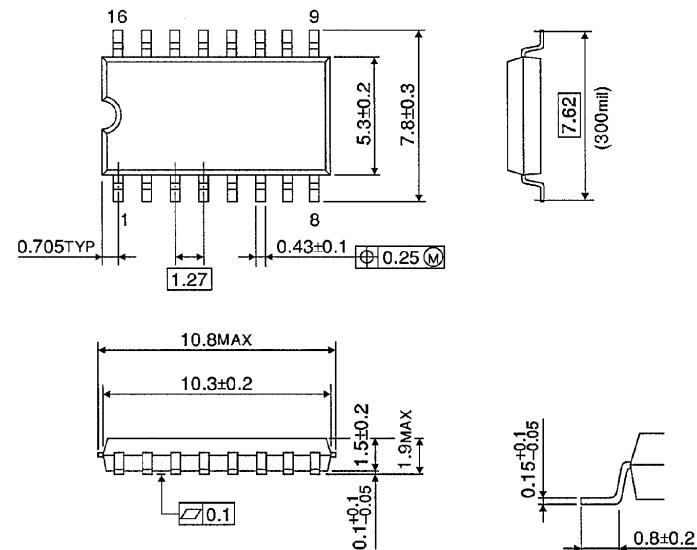
Unit in mm



Weight : 1.00g (Typ.)

**SOP 16PIN (200mil BODY) OUTLINE DRAWING (SOP16-P-300-1.27)**

Unit in mm

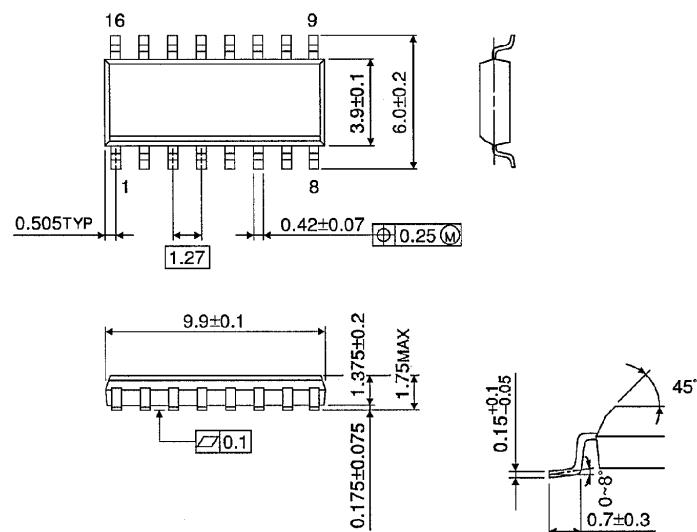


Weight : 0.18g (Typ.)

**SOP 16PIN (150mil BODY) OUTLINE DRAWING (SOL16-P-150 -1.27)**

Unit in mm

(Note) This package is not available in Japan.



Weight : 0.13g (Typ.)